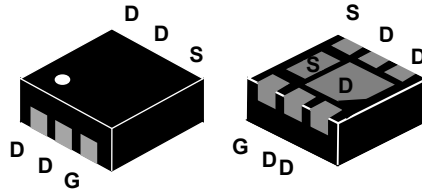
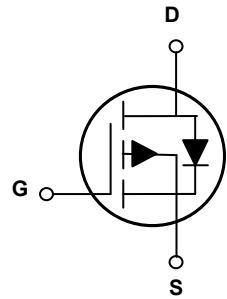


## Main Product Characteristics

$BV_{DSS}$	-30V
$R_{DS(ON)}$	23m $\Omega$ (Max.)
$I_D$	-10A



DFN2x2-6L



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFB3123 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 25$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	-10	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		-8	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	-40	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	54	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	-33	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	2.2	W
Power Dissipation-Derate above $25^\circ\text{C}$		0.018	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	56.8	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

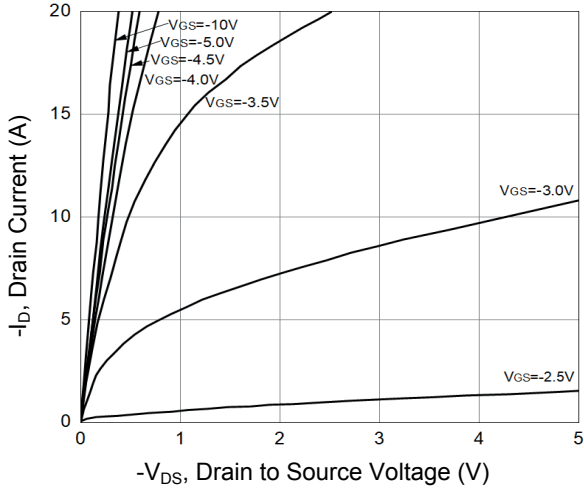
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	-	-0.03	-	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-27V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	-1	$\mu A$
		$V_{DS}=-24V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	-	-10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-8A$	-	18	23	m $\Omega$
		$V_{GS}=-4.5V, I_D=-6A$	-	25	30	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.1	-1.6	-2.9	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	4	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	gfs	$V_{DS}=-10V, I_D=-8A$	-	6.8	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=-15V, I_D=-5A, V_{GS}=-4.5V$	-	11	17	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	3.4	6	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	4.2	8	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=-15V, R_G=6\Omega, V_{GS}=-10V, I_D=-1A$	-	5.8	11	nS
Rise Time <sup>3,4</sup>	$t_r$		-	18.8	36	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	46.9	90	
Fall Time <sup>3,4</sup>	$t_f$		-	12.3	23	
Input Capacitance	$C_{iss}$	$V_{DS}=-15V, V_{GS}=0V, F=1\text{MHz}$	-	1250	2500	pF
Output Capacitance	$C_{oss}$		-	160	320	
Reverse Transfer Capacitance	$C_{rss}$		-	90	180	
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V,$ Force Current	-	-	-10	A
Pulsed Source Current	$I_{SM}$		-	-	-40	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	-	-	-1	V

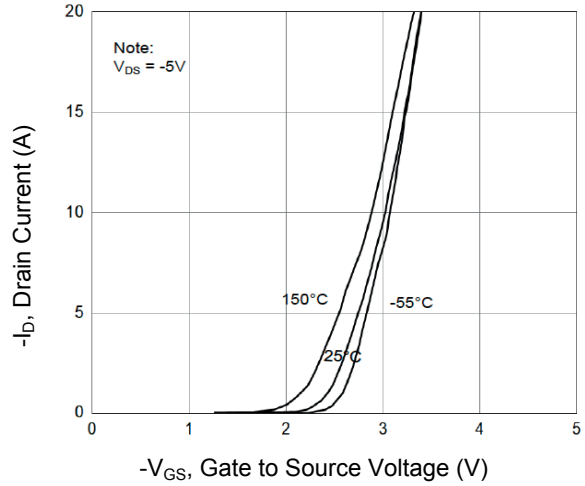
Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-25V, V_{GS}=-10V, L=0.1\text{mH}, I_{AS}=-33A$ , starting  $T_J=25^\circ\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

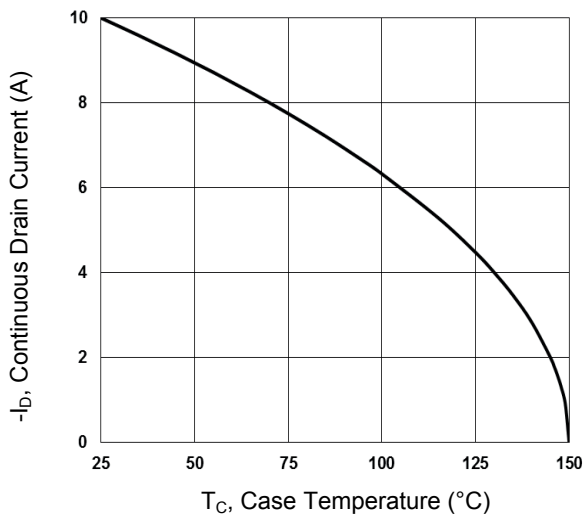
**Typical Electrical and Thermal Characteristic Curves**



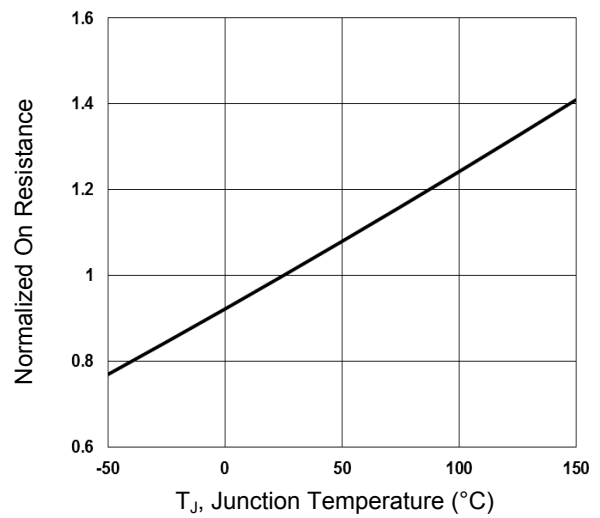
**Figure 1. Typical Output Characteristics**



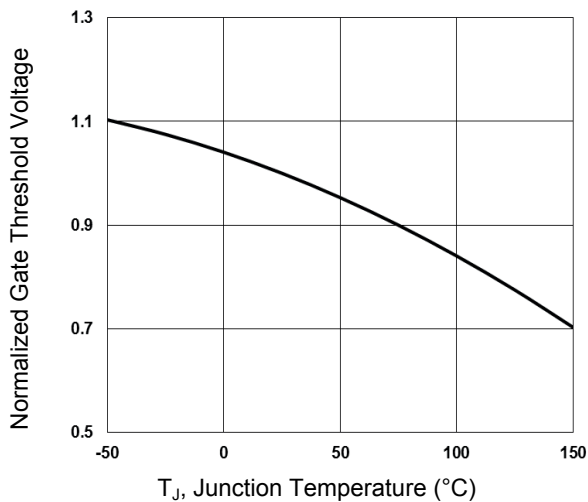
**Figure 2. Typical Transfer Characteristics**



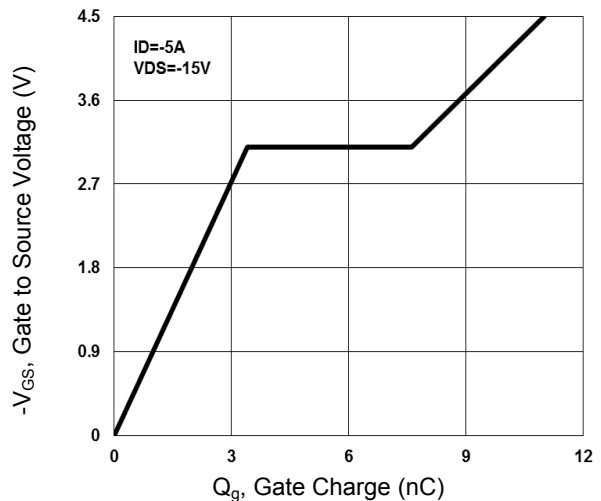
**Figure 3. Continuous Drain Current vs.  $T_C$**



**Figure 4. Normalized  $R_{DS(on)}$  vs.  $T_J$**

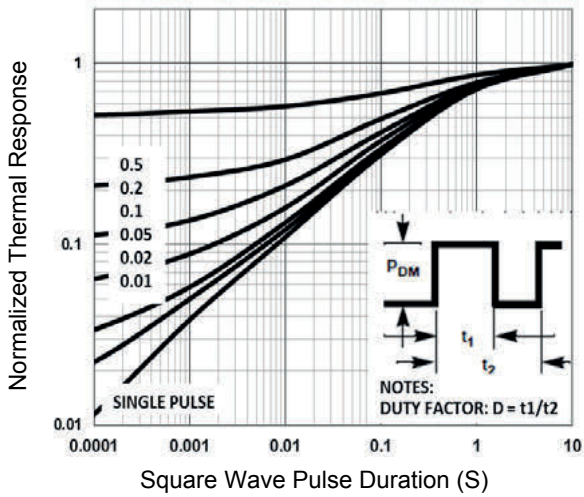


**Figure 5. Normalized  $V_{GS(th)}$  vs.  $T_J$**

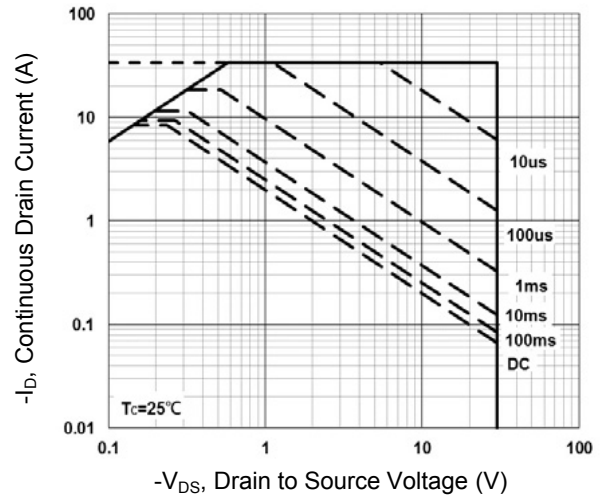


**Figure 6. Gate Charge Waveform**

**Typical Electrical and Thermal Characteristic Curves**

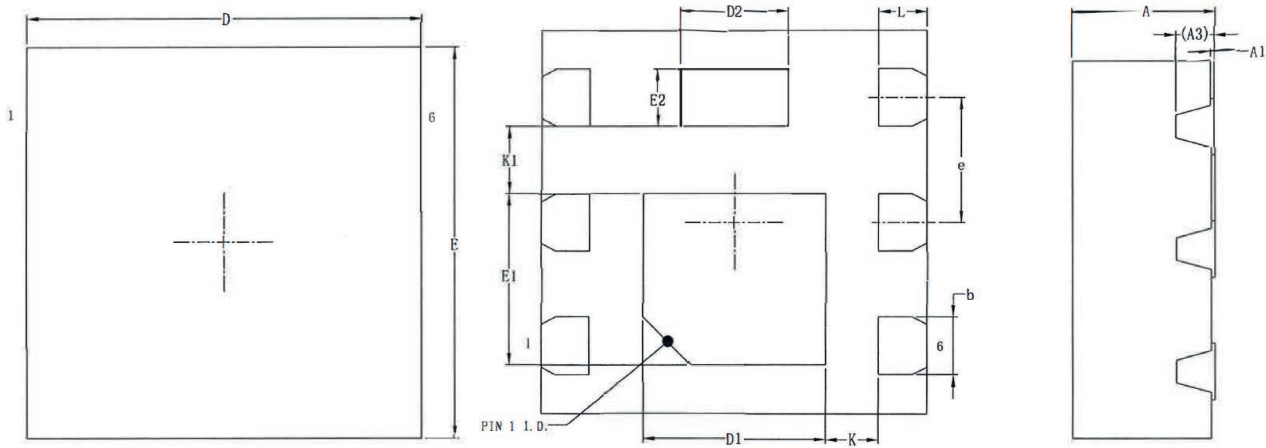


**Figure 7. Normalized Transient Impedance**



**Figure 8. Maximum Safe Operation Area**

### Package Outline Dimensions (DFN2x2-6L)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A3	0.203 REF		0.008 REF	
b	0.25	0.35	0.010	0.014
D	1.90	2.10	0.075	0.083
D1	0.85	1.05	0.033	0.041
D2	0.46	0.66	0.018	0.026
E	1.90	2.10	0.075	0.083
E1	0.80	1.00	0.031	0.039
E2	0.20	0.40	0.008	0.016
e	0.650 BSC		0.026 BSC	
L	0.25	0.30	-	0.012
K	0.275 REF		0.011 REF	
K1	0.350 REF		0.014 REF	

### Order Information

Device	Package	Marking	Packaging	SPQ
GSFB3123	DFN2x2-6L	BXY* (Varied by lot)	Tape & Reel	3,000 pcs / Reel